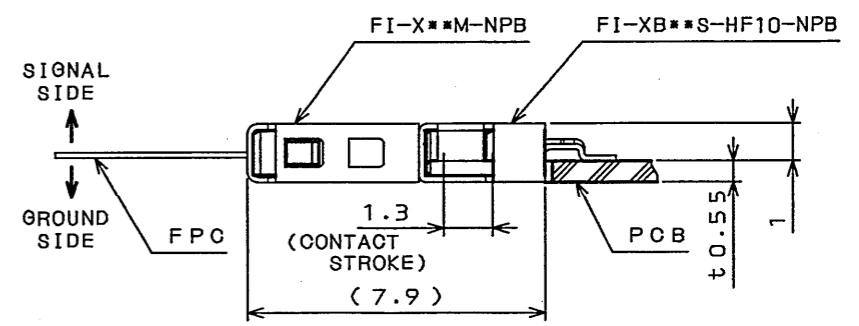
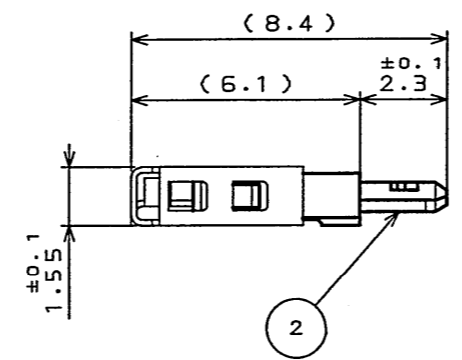
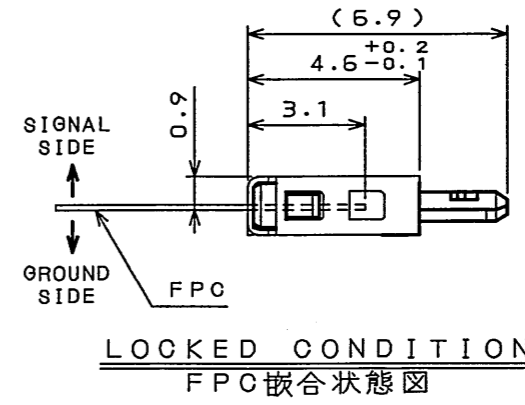
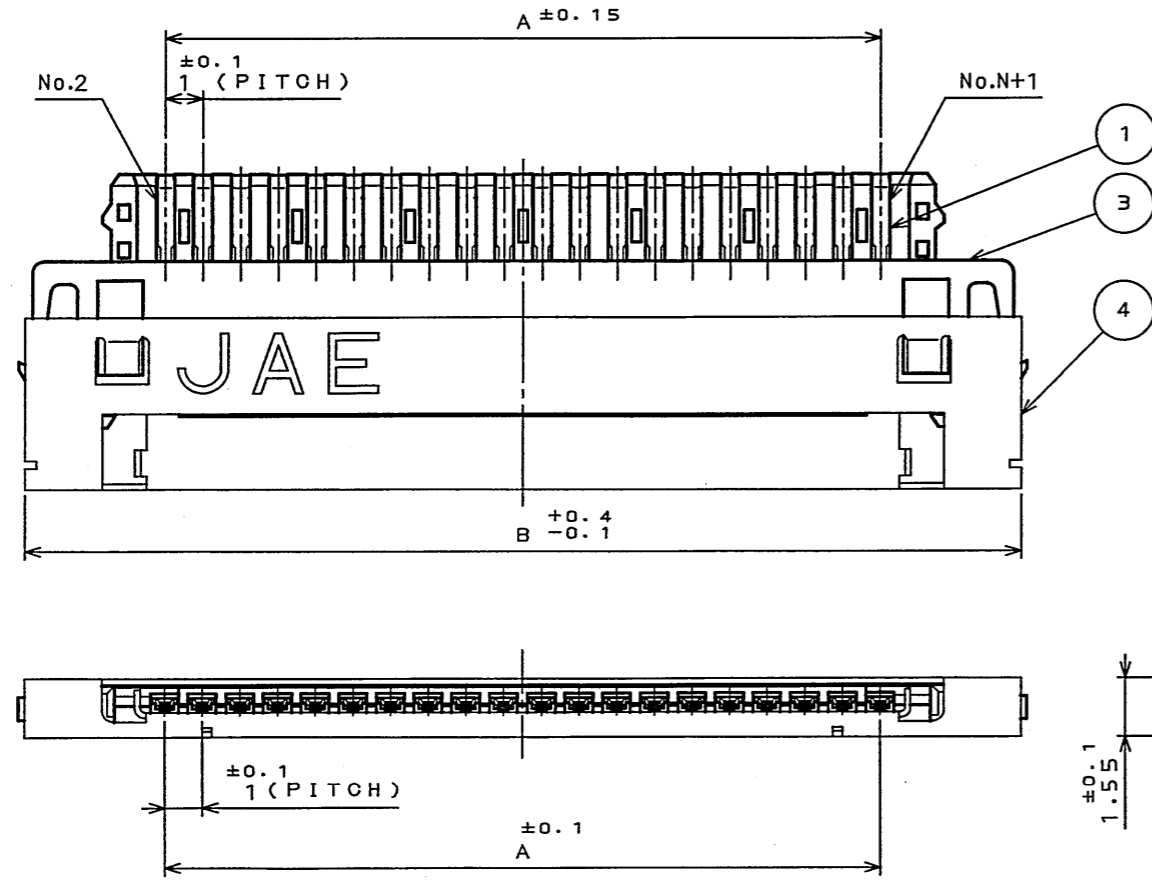


SJ100648
図号(DRAWING NO.)

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.



MATED CONDITION (REF.)
嵌合状態図(参考)

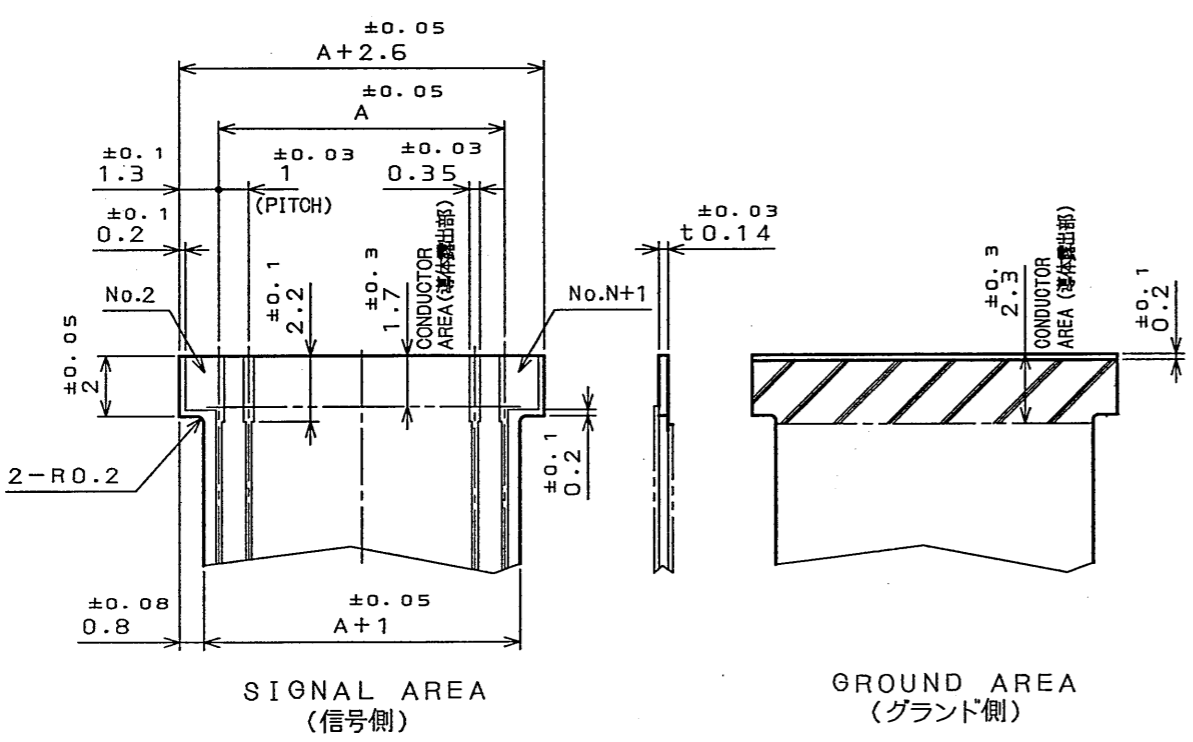


TABLE 1

NO. OF CONTACTS (N)	DIMENSION A	DIMENSION B
14	13	20.5
20	19	26.5

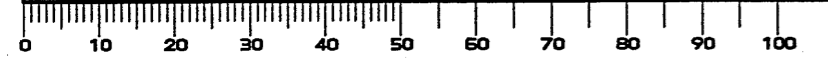
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	SHELL	1	COPPER ALLOY	TIN PLATING	
3	INSULATOR	1	GLASS FILLED 4-6N7		UL94 V-0 BEIGE
2	GROUND PLATE	1	COPPER ALLOY	TIN PLATING	
1	CONTACT	N	COPPER ALLOY	GOLD (0.1 μm MIN) OVER NICKEL	MATING FPC AREA: (LEAD FREE) TIN/TIN ALLOY OVER NICKEL

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE) 28.Jan.2004	製図 DR. H.SAKURADA	名称 (TITLE) FI-X**M-NPB (FPC SIDE)	図面番号 (DRAWING NO.) SJ100648
公差 (GENERAL TOLERANCE)	公差 (DIMENSION)	角度 (ANGLES)	製造 (MFG.)	承認 (APPD.)
±0.8	±0.4	° ±	担当 (CHK.) T.YAMAJI	承認 (APPD.) M. Suzuki
±0.4	±0.1	°X ±	査閲 (APPD.) Y. Ichijima	承認 (APPD.) Y. Ichijima
±0.1	±0.05		重量 (WEIGHT)	
±0.05				

LEAD FREE この製品は鉛フリー品です

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DOF-0-212E(03.08)



SIZE A3